APPLICA	BLE STAN	NDARD									
	OPERATING TEMPERATURE RANGE				STORAGE TEMPERA	TORAGE EMPERATURE RANGE		-10 °C TO +60 °C (NOTE2)			
RATING	VOLTAGE		250 V AC		APPLICAE CONNEC ⁻		DE1E : 0.0		. 50		
	CURRENT		AWG20 TO 24: 3A AWG26: 2A AWG28: 1A AWG30: 0.5A			VOLTAG	E	AC 30V AWG20 TO 22:	3A		
					UL, CSA	CURRENT		AWG20 TO 22: 3A AWG24 TO 28: 1A AWG30: 0.5A			
			SPEC	IFICA	TIONS			71114001	J. 071		
IT	EM		TEST METHOD				REQU	JIREMENTS	QT	АТ	
CONSTR	RUCTION										
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT			NT. ACC	ACCORDING TO DRAWING.				Х	
MARKING		CONFIRMED VISUALLY.							Х	Х	
ELECTR	IC CHARA	ACTERIS	STICS		•				•		
		20 mV MAX, 1 mA(DC OR 1000 Hz).			30 n	30 mΩ MAX.				-	
INSULATION RESISTANCE		500 V DC.			1000	1000 MΩ MIN.				-	
		650 V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				_	
MECHAN	NICAL CH	ARACTE	RISTICS						X	I	
MECHANICAL OPERATION		50 TIMES	50 TIMES INSERTIONS AND EXTRACTIONS.			CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			Х	_	
VIBRATION						 NO ELECTRICAL DISCONTINUITY OF 1 μs. NO DAMAGE, CRACK OR LOOSENESS OF 			Х	_	
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				PARTS.				_	
ENVIRO	NMENTAL	CHARA	ACTERISTICS		,						
RAPID CHANGE OF TEMPERATURE		TIME $30 \rightarrow 5 \text{ MAX} \rightarrow 30 \rightarrow 5 \text{ MAX} \text{ min}$			min 2 IN 3 N	 CONTACT RESISTANCE: 30 mΩ MAX. INSULATION RESISTANCE: 1000 MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				_	
DAMP HEAT (STEADY STATE)		EXPOSE	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			 ① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				-	
RESISTANCE TO SOLDERING HEAT		1) / 10 10 11 11 10 00 12 11 11 10 11 11 11 11 11 11 11 11 11 11				NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				_	
SOLDERABILITY		SOLDER	FRED AT SOLDER TEMPERATURE, FOR IMMERSING DURATION, 5 s.			SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				_	
1.				T							
COUN	D	ESCRIPTIO	ON OF REVISIONS		DESIGNED			CHECKED		DATE	
REMARKS NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT.						APPRO	OVED	KI. AKIYAMA	15. 05. 23		
OTE3:APPL			ITION OF LONG TERM STORAGE FOR UNUSED PRODUCT RD.AFTER PCB BOARD.OPERATING TEMPERATURE AND			ION. DESIGNED		TS. FUKUSHIMA	15. 05. 23		
•			OR INTERIM STORAGE DURIN					TS. KUMAZAWA			
	.,			<u>, </u>		DRA	WN	MI. SAKIMURA	15.0)5. 2	
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				Test	DRAW	ING NO.)	
HS.	S	SPECIFICATION SHEET			PART NO		DF	DF1EC-*P-2. 5DSA (36) CL541			
	1		ECTRIC CO., LTD.	.		1			A		



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